

DEVICE FOR SUPPORTING WORK PIECE**Abstract**

[0039] The invention provides a device for supporting work piece in a substantially planar form, in particular for supporting a semiconductor wafer during backside marking process. The device is capable of handling warped and unwarped wafers, and is compatible with various existing wafer transferring and processing techniques. The device comprises a continuous base and a continuous clamp for holding the work piece in between. The base has a planar supporting surface with a though opening therein. The clamp has a plurality of clamp jaws with individual clamping surface falling within a common planar plan. At least one ejector is coupled to the clamp for facilitating the release of work piece from the clamping surfaces.

[0040] FIG. 1 for publication